7.3 Bill of Materials (BOM)

Table 5. bq2425xEVM-150 Bill of Materials

COUNT			RefDes	Value	Description	Size	Part Number	MFR
001	002	003						
2	2	2	C1, C7	1.0uF	Capacitor, Ceramic, 25V, X5R, 20%	0805	STD	STD
1	1	1	C2	1.0uF	Capacitor, Ceramic, 16V, X5R, 10%	0402	STD	STD
1	1	1	C3	0.033uF	Capacitor, Ceramic, 25V, X5R, 10%	0402	STD	STD
1	1	1	C6	1.0uF	Capacitor, Ceramic, 6.3V, X5R, 10%	0402	STD	STD
1	1	0	C5	22uF	Capacitor, Ceramic, 10V, X5R, 20%	0805	STD	STD
0	0	1	C5	1.0uF	Capacitor, Ceramic, 10V, X5R, 20%	0805	STD	STD
1	1	0	C4	1.0uF	Capacitor, Ceramic, 10V, X5R, 20%	0805	STD	STD
0	0	1	C4	22uF	Capacitor, Ceramic, 10V, X5R, 20%	0805	STD	STD
2	2	2	D1-2	LTST-C190GKT	Diode, LED, Green, 2.1-V, 20-mA, 6-mcd	0603	LTST-C190GKT	Lite On
1	1	1	J1	1050170001	Connector, SMT, Micro USB-B	5x7.5 mm	1050170001	Molex
1	1	1	J14	N2510-6002RB	Connector, Male Straight 2x5 pin, 100mil spacing, 4 Wall	0.338 x 0.788 inch	N2510-6002RB	3M
9	9	9	J2 J4-5 J7-8 J10-11 J13 J15	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	0.100 inch x 2	PEC02SAAN	Sullins
4	4	4	J3 J6 J9 J12	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25 inch	ED555/2DS	OST
4	4	4	JP1 JP8-10	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	0.100 inch x 2	PEC02SAAN	Sullins
4	4	4	JP3, 4, 6, 7	PEC03SAAN	Header, Male 3-pin, 100mil spacing,	0.100 inch x 3	PEC03SAAN	Sullins
1	1	1	L1	1.0uH	Inductor, SMT ±30%	2x2.5 mm	1239AS-H-1R0M (DFE252012C) see Note 8	Toko
1	1	1	R10	274K	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	1	1	R11	100K	Resistor, Chip, 1/16W, 1%	0603	STD	STD
2	2	2	R1-2	200	Resistor, Chip, 1/16W, 1%	0603	STD	STD
2	2	2	R3-4	1.50K	Resistor, Chip, 1/16W, 1%	0603	STD	STD
2	2	2	R5-6	20.0K	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	1	1	R7	100K	Potentiometer, 3/8 Cermet, Twelve-Turn	0.25x0.17 inch	3266W-1-104LF	Bourns
1	1	1	R8	267	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	1	1	R9	249	Resistor, Chip, 1/16W, 1%	0603	STD	STD
15	15	15	TP1-15	5002	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 inch	5002	Keystone
1	0	0	U1	BQ24250YFF	IC, 2.0A Single Input I2C/Standalone Switch-Mode Li-Ion Battery Charger	BGA	BQ24250YFF	TI
0	1	0	U1	BQ24251YFF	IC, 2.0A Single Input I2C/Standalone Switch-Mode Li-Ion Battery Charger	BGA	BQ24251YFF	TI
0	0	1	U1	BQ24257YFF	IC, 2.0A Single Input I2C/Standalone Switch-Mode Li-Ion Battery Charger	BGA	BQ24257YFF	TI
0	0	0	JP2, 5	Open	Header, Male 3-pin, 100mil spacing,	0.100 inch x 3	PEC03SAAN	Sullins
5	3	3	--	--	Shunt, 100-mil, Black	0.100	929950-00	3M
1	1	1	--	--	PCB		PWR150	Any

Notes:
1. These assemblies are ESD sensitive, observe ESD precautions.
2. These assemblies must be clean and free from flux and all contaminants. Use of no-clean flux is not acceptable.
3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
4. The ICs of the first build of these EVMs have a different marker.
5. Ref designators marked with an asterisk ('**') cannot be substituted. All other components can be substituted with equivalent MFG's components.
6. Install shunts on:
   - JP3 between CE and LOW (all)
   - JP4 between TS and FIX (all)
   - JP8 Install (all)
   - JP5 between D–/EN2 and Low (bq24250 only)
   - JP2 between D+/EN1 and Low (bq24250 only)
7. The first cycle of this EVM, the Top Marking of the IC is different from the latter cycles.
8. TFM252010A-1ROM from TDK inductor can be used.

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